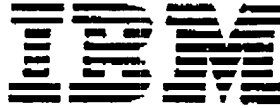


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE	
In re application of: <b>Leah Pastel</b>	Date: <b>May 9, 2006</b>
Serial Number: <b>10/595,526</b>	Examiner:
Filed: <b>April 26, 2006</b>	Group Art Unit: Confirmation No.:
Title: <b>HOT SWITCHABLE VOLTAGE BUS FOR IDDQ CURRENT MEASUREMENTS</b>	IBM Corporation D/18G, B/300, Zip 482 2070 Route 52 Hopewell Junction, NY 12533-6531

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 CFR 1.56, and further  
pursuant to 37 CFR 1.97 and 37 CFR 1.98, Applicants hereby respectfully submit  
copies of the non-US patents and publications as listed on Form PTO-1449, attached  
hereto.

Pursuant to 37 CFR 1.97 (b) (3), no fee is believed to be necessary.

Respectfully submitted,  
**Leah Pastel**

By: James J. Cioffi  
James J. Cioffi, Attorney  
Registration No. 51,564  
Tel. (845)894-3363

Enclosure

BUR920030080US1

-1-

PAGE1 OF 1

FORM PTO-1449 (Modified)  LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT  (Use several sheets if necessary)	ATTY. DOCKET NO. <b>BUR920030080US1</b>	SERIAL NO. <b>10/595,526</b>
	APPLICANT: <b>Leah Pastel</b>	
	FILING DATE: <b>4-26-06</b>	GROUP:

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

EXAMINER INITIALS		DOCUMENT NUMBER	ISSUED DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPRO.)
	A1	6043672	03-28-00	Sugasawara			
	A2	5757203	05-26-98	Brown			
	A3	5742177	04-21-98	Kalb, Jr.			
	A4	5726997	03-10-98	Teene			
	A5	5670890	09-23-97	Colwell et al			
	A6	5371457	12-06-94	Lipp			
	A7	6538314	03-25-03	Buffet et al			
	A8	6342790	01-29-02	Ferguson et al			
	A9	6118293	09-12-00	Manhaeve et al			
	B1	5917331	06-29-99	Persons			
	B2	5721495	02-24-98	Jennion et al			
	B3	5773990	06-30-98	Wilstrup et al			

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	B4							
	B5							
	B6							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

	C1	IBM Technical Disclosure Bulletin, Vol. 28, No.1, June 1985, Bossen, et al, "Yield and Reliability Enhancement Via Redundancy for VLSI Chips And Wafers", pp 36-42
	C2	IBM Technical Disclosure Bulletin, Vol. 20, No.11A, April 1978, Fox, et al, "Flexible Voltage Distribution In Custom Semiconductor Circuit Chips", pp 4378-4379

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.